

IN THE CLAIMS

Claims 1-13 have been previously cancelled without prejudice.

Please amend claim 14.

Please enter the pending claims as follows:

1. – 13. (Cancelled)

14. (Currently Amended) A self-aligned mechanical joint comprising:
a bump on a die, said bump comprising electroplated copper;
and
a solder on a substrate wherein said solder was reflowed by
indirect heat through conduction from said bump upon absorption of
microwave energy by said die.

15. (Original) The mechanical joint of claim 14 wherein said microwave energy has variable frequency.

16. (Original) The mechanical joint of claim 14 wherein said bump was reflowed by microwave energy.

17. (Original) The mechanical joint of claim 16 wherein said microwave energy has variable frequency.